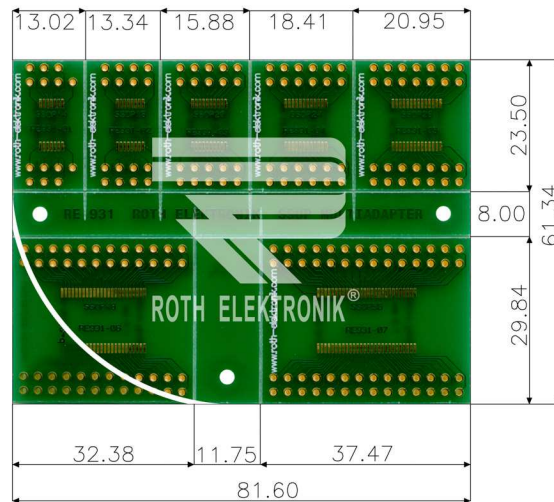


RE931

- Epoxy fibre-glass 1.50 mm
- Double-sided 35 µm Cu
- Plated through holes (PTH)
- Surface chem. Ni/Au with solder stop mask
- Adaption circuit board for 7 different SSOP's
- Pitch: 0.65 mm & 0.635 mm
- Hole diameter 1.00 mm
- Prescratched rated break point for the separation of individual moduls from the board
- Size 61.40 x 81.70 mm

Module-No. Pitch mil Pin Size (mm)

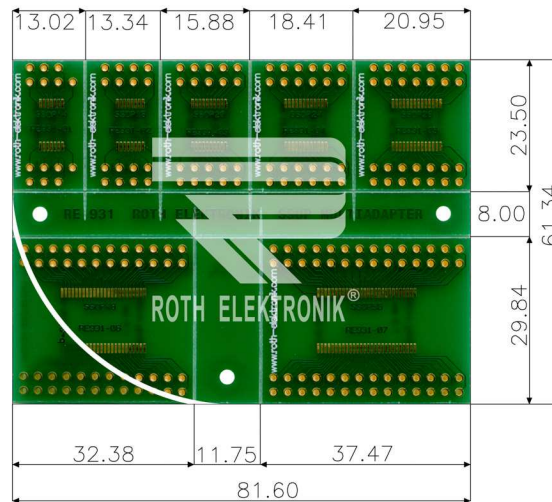
RE931-01 0.650 mm 25,6 14 5.300 (208 mil) RE931-02 0.650 mm 25,6 16 5.300 (208 mil) RE931-03 0.650 mm 25,6 20 5.300 (208 mil) RE931-04 0.650 mm 25,6 24 5.300 (208 mil) RE931-05 0.650 mm 25,6 28 5.300 (208 mil) RE931-06 0.635 mm 25,0 48 7.500 (295 mil) RE931-07 0.635 mm 25,0 56 7.500 (295 mil)



RE931

- Epoxydglashartgewebe FR4 1,50 mm
 - Zweiseitig 35 µm Cu
 - Durchkontaktiert (PTH)
 - Oberfläche chem. Ni/Au mit Lötstopplack beschichtet
 - Adaptionplatine für 7 verschiedene SSOP's
 - Pitch: 0,65 mm & 0,635 mm
 - Lochdurchmesser 1,00 mm
 - vorgertizte Sollbruchstellen zum Trennen einzelner Module von der Platine
 - Größe 61,40 x 81,70 mm
- Modul-Nr. Pitch mil Pin Größe (mm)

RE931-01 0,650 mm 25,6 14 5,300 (208 mil) RE931-02 0,650 mm 25,6 16 5,300 (208 mil) RE931-03 0,650 mm 25,6 20 5,300 (208 mil) RE931-04 0,650 mm 25,6 24 5,300 (208 mil) RE931-05 0,650 mm 25,6 28 5,300 (208 mil) RE931-06 0,635 mm 25,0 48 7,500 (295 mil) RE931-07 0,635 mm 25,0 56 7,500 (295 mil)

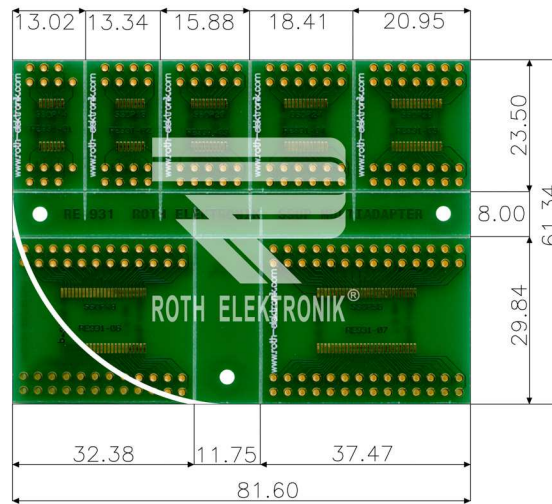


RE931

- Fibre de verre époxyde FR4 1,50 mm
- Double face 35 µm Cu
- Métallisation des trous (PTH)
- Surface avec Ni/Au chimique et un laque d'arrêt de soudure
- Adaptateur pour 7 SSOP différents
- Pitch: 0,65 mm & 0,635 mm
- Perforation 1,00 mm Ø
- Points destinés à la rupture pour séparer des modules individuels de la platine
- Dimensions 61,40 x 81,70 mm

Module-No. Pitch mil Pin Dimensions (mm)

RE931-01 0,650 mm 25,6 14 5,300 (208 mil) RE931-02 0,650 mm 25,6 16 5,300 (208 mil) RE931-03 0,650 mm 25,6 20 5,300 (208 mil) RE931-04 0,650 mm 25,6 24 5,300 (208 mil) RE931-05 0,650 mm 25,6 28 5,300 (208 mil) RE931-06 0,635 mm 25,0 48 7,500 (295 mil) RE931-07 0,635 mm 25,0 56 7,500 (295 mil)



RE931

- Fibra de vidrio epoxídica FR4 1,50 mm
- Por dos lados 35 µm de Cu
- Agujeros con contactos metalizados (PTH)
- Superficie terminal química de Ni/Au y una máscara de inhibidora de la soldadura
- Adaptador para 7 SSOP diferentes
- Diámetro de agujeros 1,00 mm
- Pitch: 0,65 mm & 0,635 mm
- Puntos de ruptura controlada prerrayados para separar módulos individuales de la placa de circuito impreso
- Tamaño 61,40 x 81,70 mm

Modulos-No. Pitch mil Pin Tamaño (mm)

RE931-01 0,650 mm 25,6 14 5,300 (208 mil) RE931-02 0,650 mm 25,6 16 5,300 (208 mil) RE931-03 0,650 mm 25,6 20 5,300 (208 mil) RE931-04 0,650 mm 25,6 24 5,300 (208 mil) RE931-05 0,650 mm 25,6 28 5,300 (208 mil) RE931-06 0,635 mm 25,0 48 7,500 (295 mil) RE931-07 0,635 mm 25,0 56 7,500 (295 mil)